

Title (en)

IMPROVED BONDING MEANS AND METHODS FOR POLYMER COATED DEVICES.

Title (de)

VERBESSERTE KLEBMITTEL UND VERFAHREN ZUR HERSTELLUNG VON POLYMERBESCHICHTETEN VORRICHTUNGEN.

Title (fr)

ORGANES AMELIORES DE LIAISON ET PROCEDES PERMETTANT D'OBTENIR DES DISPOSITIFS RECOUVERTS DE POLYMERES.

Publication

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Application

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Priority

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Abstract (en)

[origin: WO8303943A1] Improved characteristics can be obtained in electronic devices (20, 30, 40) by utilizing comparatively soft organic dielectric layers (22, 24, 32, 34, 42, 44) to support one or more conductor layers (23, 25, 33, 35, 43, 45). Bonding problems are avoided by providing a means and method which locates the bonding pads (27, 37, 47) directly on the substrate (21, 31, 41) rather than on the softer organic dielectric layers (22, 24, 32, 34, 42, 44). Fewer masking steps are required compared to the prior art.

Abstract (fr)

On peut obtenir des dispositifs électroniques (20, 30, 40) possédant des caractéristiques améliorées en utilisant des couches diélectriques organiques relativement souples (22, 24, 32, 34, 42, 44) comme supports pour une ou plusieurs couches conductrices (23, 25, 33, 35, 43, 45). Les problèmes de liaison sont éliminés par un organe et par un procédé permettant de disposer les blocs de liaison (27, 37, 47) directement sur le substrat (21, 31, 41) plutôt que sur les couches diélectriques organiques plus souples (22, 24, 32, 34, 42, 44). Moins d'étapes de masquage sont nécessaires par rapport à l'art antérieur.

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